

CE DECLARATION OF PERFORMANCE

According to Regulation (EU) No. 305 of the European Parliament and the Council of 9 March 2011

DOP No	DOP-225
1 Unique identification product code	Egger Eurospan EAC E1 P5/Protect CE Code: 225 8 to 40 mm (board thickness)
2 Intended use	Chipboard P5 (EN312) for internal use as a structural component in humid conditions
3 Manufacturer	EGGER group – Fritz EGGER GmbH & Co. OG Weiberndorf 20 A-6380 St. Johann/Tyrol, Austria web: www.egger.com
4 not applicable	
5 System of assessment and verification of constancy of performance	System 2+
6 Harmonised standard	EN 13986:2004+A1:2015
Notified body	0380 Institut Technologique FCBA 10, Rue Galilée 77420 Champs-sur-Mame France the certification and has issued the certificate 0380-CPR-0366

7 Declaration of performance/s

Essential characteristics *1	Unit						Harmonised technical spezifikation
Board thickness	mm	8 -13	13 -20	20 - 25	25 - 32	32 - 40	
Strength							EN13986:2004+A1:2015
Tension	N/mm²	-	8.5	7.4	6.6	5.6	
Compression	N/mm²	-	11.8	10.3	9.8	8.5	
Bending	N/mm²	-	13.3	11.7	10.0	8.3	
Panel shear	N/mm²	-	6.5	5.9	5.2	4.8	
Planar shear	N/mm²	-	1.7	1.5	1.3	1.2	
Stiffness (MOE)							
Tension and Compression	N/mm²	-	1900	1800	1500	1400	
Bending	N/mm²	-	3300	3000	2600	2400	
Panel shear	N/mm²	-	930	860	750	690	
Punching shear							
as point load strength and point load stiffness		NPD					
Impact resistance:							
(acc. to EN 12871)		Pass					
Bending strenth	N/mm²	18	16	14	12	10	
Internal bond	N/mm²	0.45	0.45	0.40	0.35	0.30	
Bending modulus of elasticity	N/mm²	2550	2400	2150	1900	1700	
Thickness swelling 24h	%	11	10	10	10	9	
Swelling in thickness after cyclic test EN 321	%	12	12	11	10	9	
Internal bond after cyclic test	N/mm²	0.25	0.22	0.20	0.17	0.15	
Formaldehyde emission class		E1					
Reaction to fire *2		E	D -s2, d0	D-s2, d0	D-s2, d0	D-s2, d0	
Without air gap behind the board							
With or without air gap ≤ 22 mm behind the board		E	D-s2, d2	D-s2, d2	D-s2, d2	D-s2, d2	
Without air gap > 22 mm behind the board		E	E	D-s2, d0	D-s2, d0	D-s2, d0	
With air gap > 22 mm behind the board		E	E	D-s2, d0	D-s2, d0	D-s2, d0	
Water vapour permeability							
wet	μ	15					
dry	μ	50					
Airborne sound insulation		NPD					
Sound absorption	α	0.10 / 0.25					
Thermal conductivity	W/mK	0.12					
Biological durability		1					
Content of PCP	ppm	< 5					

*1 Essential characteristics are valid for following plant/s of the EGGER Group:

27 EGGER (UK) Limited
Anick Grange Road, Hexham
NE46 4JS
United Kingdom

*2 Density ≥ 600 kg/m³

8 not applicable

The performance of the product identified above is in conformity with the set of declared performance/s. This declaration of performance is issued, in accordance with Regulation (EU) No 305/2011, under the sole responsibility of the manufacturer identified above.

Signed for and on behalf of the manufacturer by

St. Johann / Tyrol 18.07.2019



Manfred Riepertinger

Core Material Management / Product Sustainability
Group